

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Takashi SHOJI</td><td>03/26/2008</td></tr><tr><td>Takekazu SAKAI</td><td>03/26/2008</td></tr><tr><td>Tetsuo KUBOTA</td><td>03/26/2008</td></tr></tbody></table>		Name	Execution Date	Takashi SHOJI	03/26/2008	Takekazu SAKAI	03/26/2008	Tetsuo KUBOTA	03/26/2008
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Takashi SHOJI	03/26/2008								
Takekazu SAKAI	03/26/2008								
Tetsuo KUBOTA	03/26/2008								
RECEIVING PARTY DATA									
Name:	SHOWA DENKO K.K.								
Street Address:	13-9, Shiba Daimon 1-chome								
City:	Minato-ku, Tokyo								
State/Country:	JAPAN								
Postal Code:	105-8518								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12013246</td></tr></tbody></table>		Property Type	Number	Application Number:	12013246				
Property Type	Number								
Application Number:	12013246								
CORRESPONDENCE DATA									
Fax Number: (202)293-7860 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone: 202-293-7060									
Email: ahoward-agu@SUGHRUE.COM									
Correspondent Name: SUGHRUE MION, PLLC									
Address Line 1: 2100 PENNSYLVANIA AVENUE, N.W.									
Address Line 2: SUITE 800									
Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20037									
ATTORNEY DOCKET NUMBER:	Q89223								
NAME OF SUBMITTER:	Sheldon I. Landsman								
Total Attachments: 1 source=Assignment_04_02_08#page1.tif									

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PATENT

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REEL: 020745 FRAME: 0055

# ASSIGNMENT

Whereas, I/we

1. SHOJI Takashi
2. SAKAI Takekazu  
both of c/o SHOWA DENKO K.K.  
13-9, Shiba Daimon 1-chome, Minato-ku, Tokyo 105-8518 Japan
3. KUBOTA Tetsuo  
of c/o TAISEI Co., Ltd.  
6972, Shimo-Yoshida, Chichibu-shi, Saitama 369-1593 Japan

hereinafter called assignor(s), have invented certain improvements in

METHOD FOR ATTACHMENT OF SOLDER POWDER TO ELECTRONIC CIRCUIT BOARD AND SOLDER-ATTACHED ELECTRONIC CIRCUIT BOARD

and executed an application for Letters Patent of the United States of America therefor on

March 26, 2008; and

Whereas, SHOWA DENKO K.K.  
of 13-9, Shiba Daimon 1-chome, Minato-ku, Tokyo 105-8518, JAPAN

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including the right to claim priority under 35 U.S.C. § 119, and I/we request the Director – U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignee.

I/We hereby authorize and request my/our attorneys SUGHRUE MION, PLLC of 2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037-3213 to insert here in parentheses (Application number 12/013,246, filed January 11, 2008) the filing date and application number of said application when known.

Date: March 26, 2008

s/ Takashi Shoji  
SHOJI Takashi

Date: March 26, 2008

s/ Takekazu Sakai  
SAKAI Takekazu

Date: March 26, 2008

s/ Tetsuo Kubota  
KUBOTA Tetsuo